STD845DN40

Dual NPN high voltage transistors in a single package

Preliminary data

Features

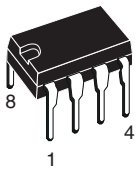
- Low $V_{CE(sat)}$
- Simplified circuit design
- Reduced component count
- Fast switching speed

Applications

- Compact fluorescent lamp (CFL) 220 V mains
- Electronic ballast for fluorescent lighting

Description

The device is a dual NPN high voltage power transistor manufactured using multi-epitaxial planar technology. It is housed in dual-island DIP-8 package with separated terminals to provide a high degree of assembly flexibility.



DIP-8

Figure 1. Internal schematic diagram

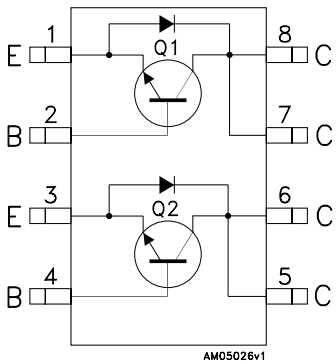


Table 1. Device summary

Order code	Marking	Package	Packaging
STD845DN40	D845DN40	DIP-8	Tube

1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{CBO}	Collector-base voltage (I_E = 0)	700	V
V_{CEO}	Collector-emitter voltage (I_B = 0)	400	V
V_{EBO}	Emitter-base voltage (I_C = 0, I_B = 2 A, t_p < 10 ms)	$V_{(BR)EBO}$	V
I_C	Collector current	4	A
I_{CM}	Collector peak current (t_P < 5 ms)	8	A
I_B	Base current	2	A
I_{BM}	Base peak current (t_P < 5 ms)	4	A
P_{TOT}	Total dissipation at T_{amb} = 25 °C single transistor	TBD	W
	Total dissipation at T_{amb} = 25 °C both transistors	TBD	W
T_{STG}	Storage temperature	-65 to 150	°C
T_J	Max. operating junction temperature	150	°C

Table 3. Thermal data

Symbol	Parameter	Value	Unit
R_{thJA} (1)	Thermal resistance junction-ambient (Single transistor)	TBD	°C/W
	Thermal resistance junction-ambient (Both transistors)	TBD	°C/W

1. When mounted on 1 inch square pad of 2 oz. copper, t ≤ 10 sec.

2 Electrical characteristics

T_{case} = 25 °C unless otherwise specified.

Table 4. Electrical characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{CES}	Collector cut-off current (V_{BE} = 0)	V_{CE} = 700 V V_{CE} = 700 V T_c = 125 °C			100 500	µA µA
I_{CEO}	Collector cut-off current (I_B = 0)	V_{CE} = 400 V			250	µA
$V_{(BR)EBO}$	Emitter-base breakdown voltage (I_C = 0)	I_E = 10 mA	9		18	V
$V_{CEO(sus)}$(1)	Collector-emitter sustaining voltage (I_B = 0)	I_C = 100 mA	400			V
$V_{CE(sat)}$(1)	Collector-emitter saturation voltage	I_C = 0.5 A I_B = 0.1 A I_C = 1 A I_B = 0.2 A I_C = 2.5 A I_B = 0.5 A I_C = 4 A I_B = 1 A		 0.5	0.7 1 1.5 	V V V V
$V_{BE(sat)}$(1)	Base-emitter saturation voltage	I_C = 0.5 A I_B = 0.1 A I_C = 1 A I_B = 0.2 A I_C = 2.5 A I_B = 0.5 A			1.1 1.2 1.3	V V V
h_{FE}(1)	DC current gain	I_C = 10 mA V_{CE} = 5 V I_C = 2 A V_{CE} = 5 V	10 12		 32	
V_F	Diode forward voltage	I_F = 2 A			2.5	V
t_s t_f	Resistive load Storage time Fall time	I_C = 2 A $I_{B(on)}$ = - $I_{B(off)}$ = 400 mA V_{CC} = 125 V t_p = 30 µs		 2.5 0.2		 µs µs
t_s t_f	Inductive load Storage time Fall time	I_C = 2 A, V_{CC} = 200 V $V_{BE(off)}$ = - 5 V $I_{B(on)}$ = 400 mA R_{BB} = 0, L = 200 µH		 0.6 0.1		 µs µs

1. Pulse test: pulse duration ≤ 300 µs, duty cycle ≤ 2 %.

2.1 Electrical characteristics (curves)

Figure 2. DC current gain (V_{CE} = 1.5 V)

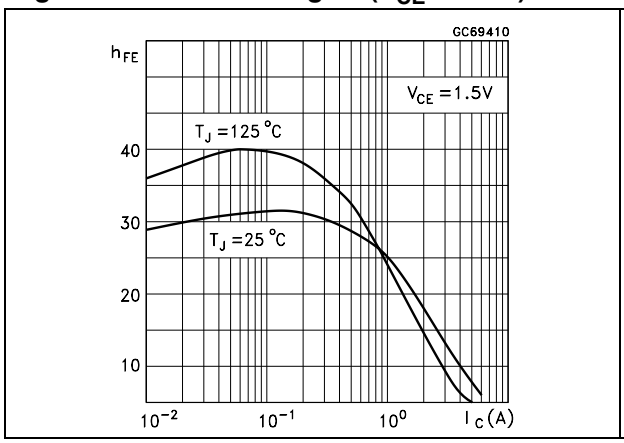


Figure 3. DC current gain (V_{CE} = 5 V)

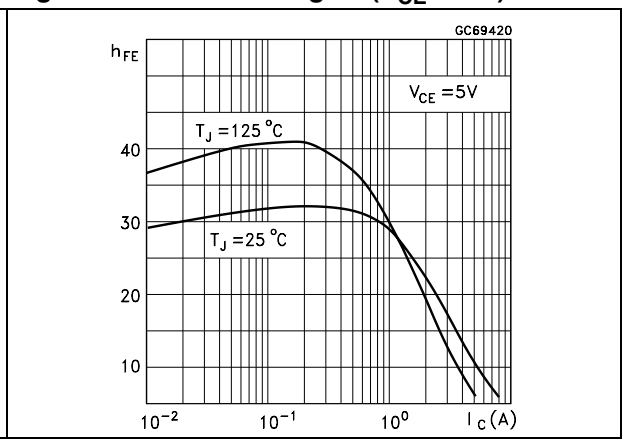


Figure 4. Collector-emitter saturation voltage

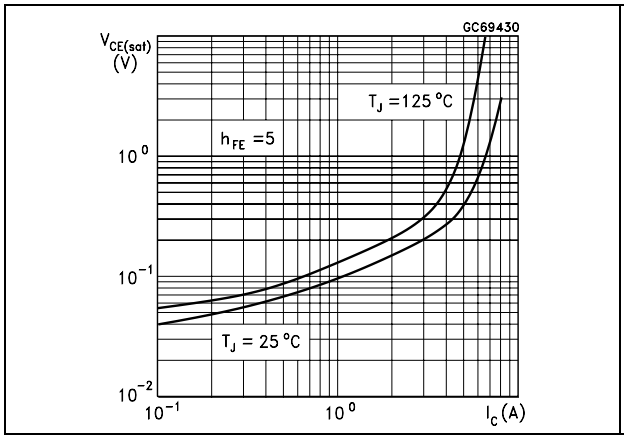


Figure 5. Base-emitter saturation voltage

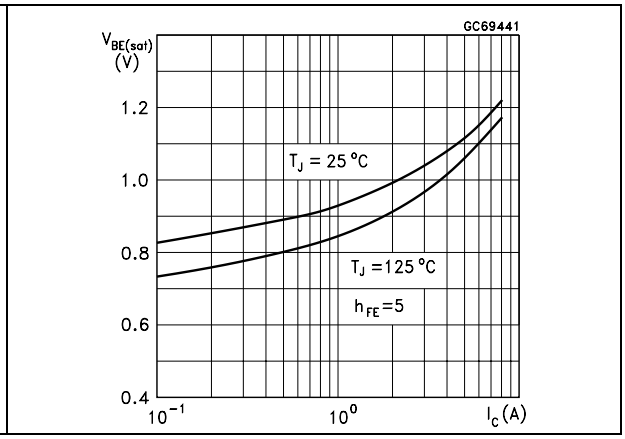


Figure 6. Inductive load fall time

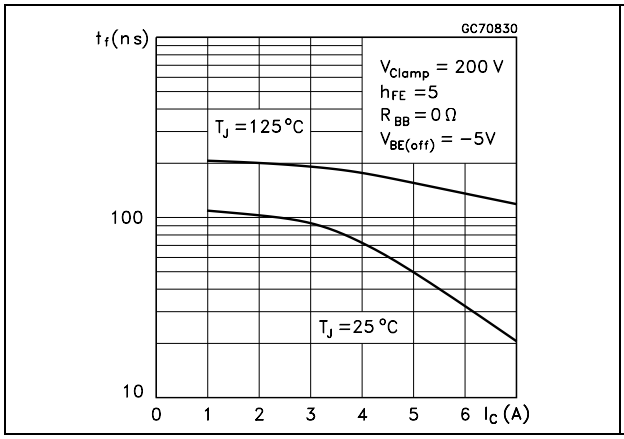


Figure 7. Inductive load storage time

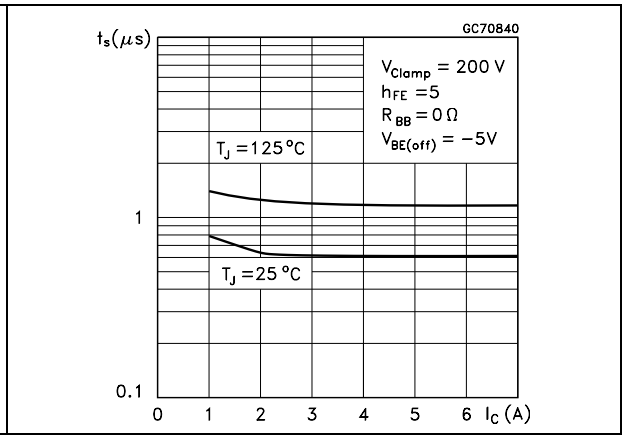


Figure 8. Resistive load fall time

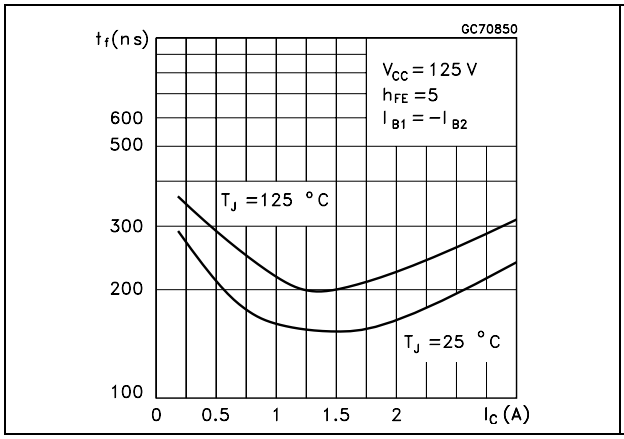


Figure 9. Resistive load storage time

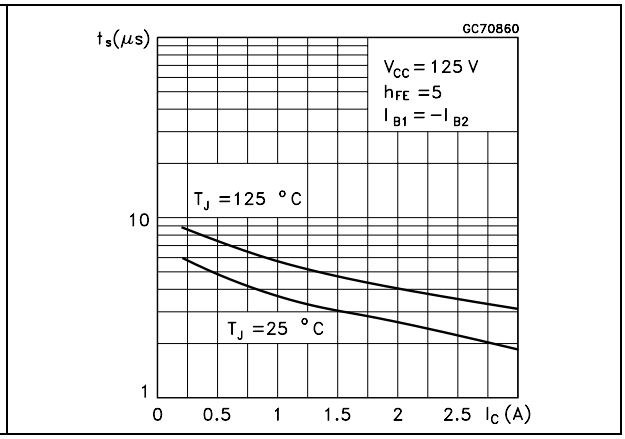
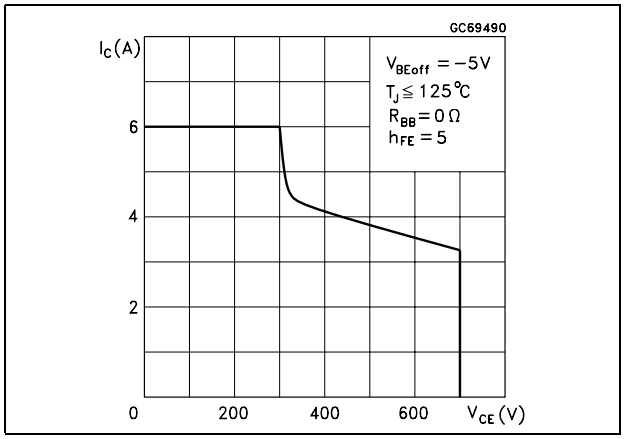
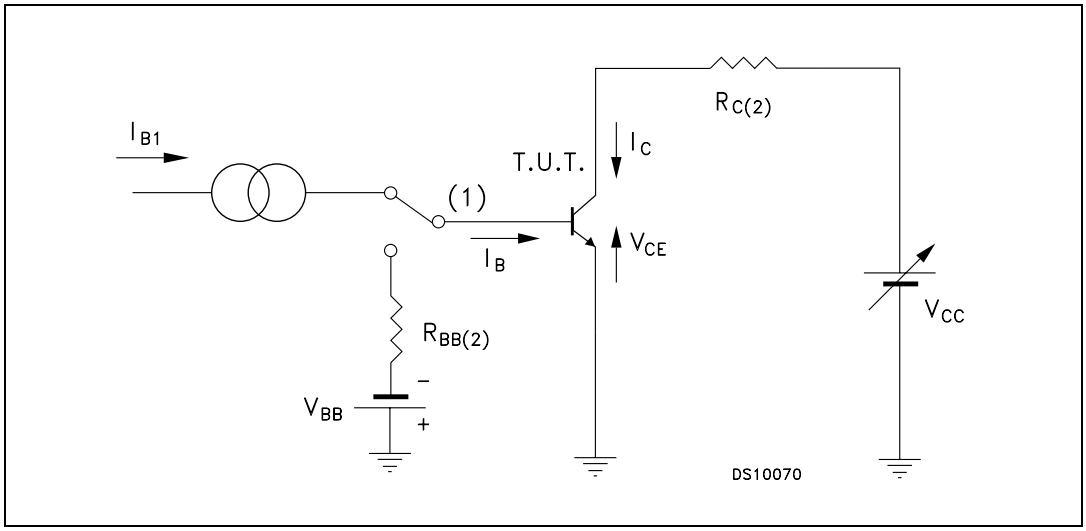


Figure 10. Reverse biased safe operating area



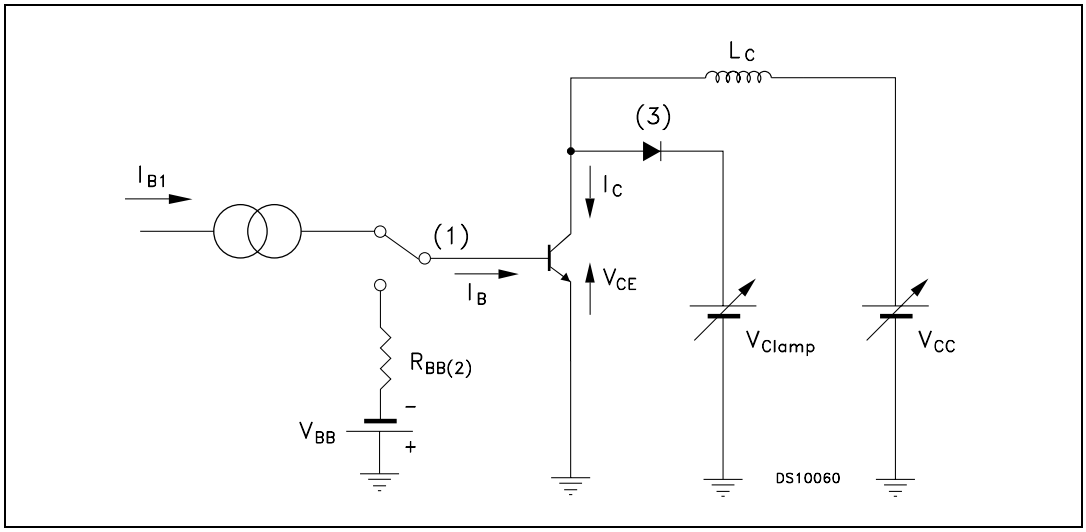
3 Test circuits

Figure 11. Resistive load switching test circuit



1. Fast electronic switch
2. Non-inductive resistor

Figure 12. Inductive load switching test circuit



1. Fast electronic switch
2. Non-inductive resistor
3. Fast recovery rectifier

4 Package mechanical data

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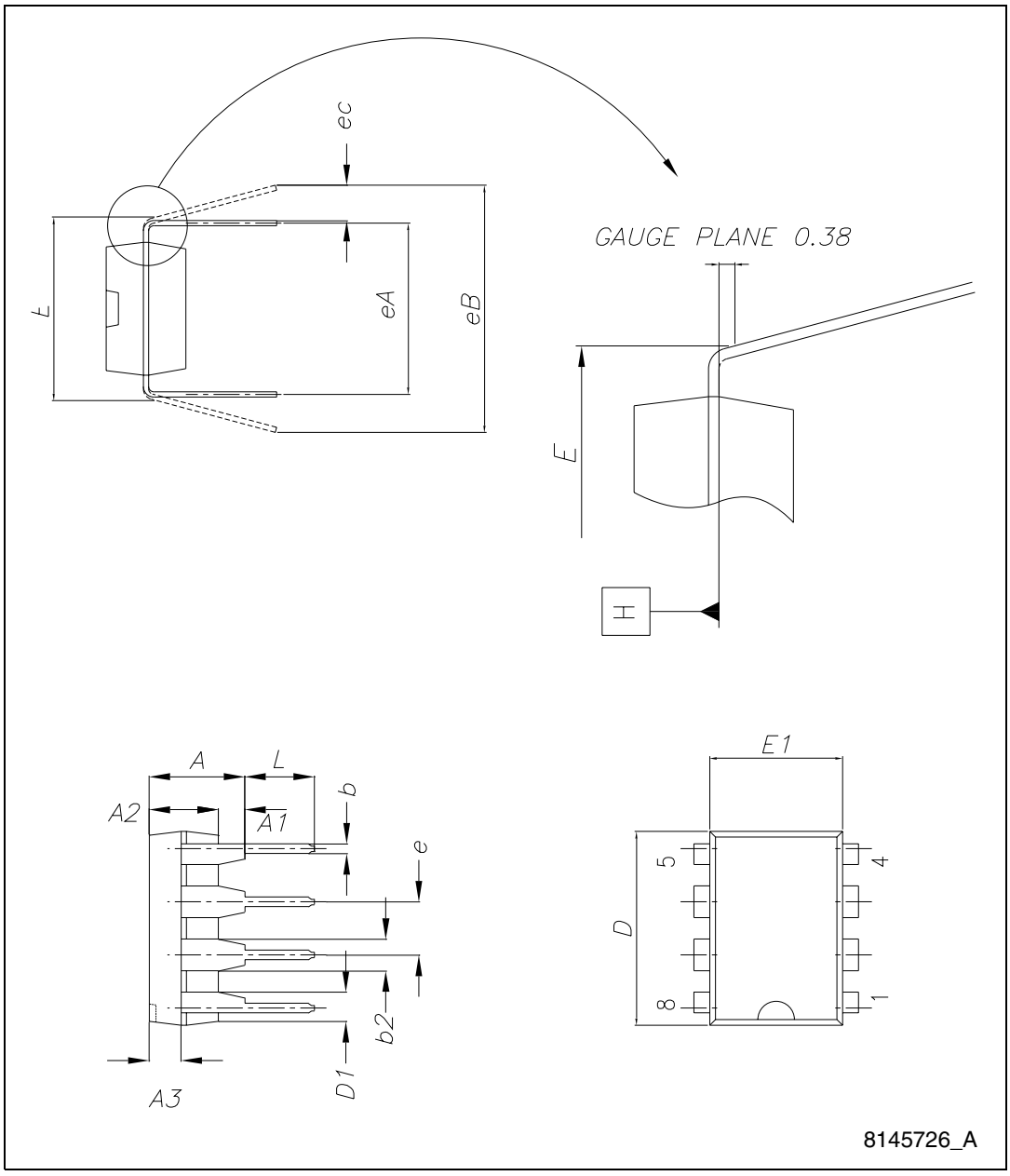
Table 5. DIP-8 mechanical data

Dim.	mm.		
	Min.	Typ.	Max.
A			4.80
A1	0.50		
A2	3.10		3.50
A3	1.40		1.60
b	0.38		0.55
b1	0.38		0.51
b2	1.47		1.57
b3	0.89		1.09
c	0.21		0.35
c1	0.20		0.30
D	9.10		9.30
D1	0.13		
E	7.62		8.25
E1	6.25		6.45
e		2.54	
eA		7.62	
eB	7.62		10.90
eC	0		1.52
L	2.92		3.81

Figure 13. Drawing dimension DIP-8



5 Revision history

Table 6. Document revision history

Date	Revision	Changes
03-Mar-2010	1	Initial release.

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